



Devices always involve interfaces:

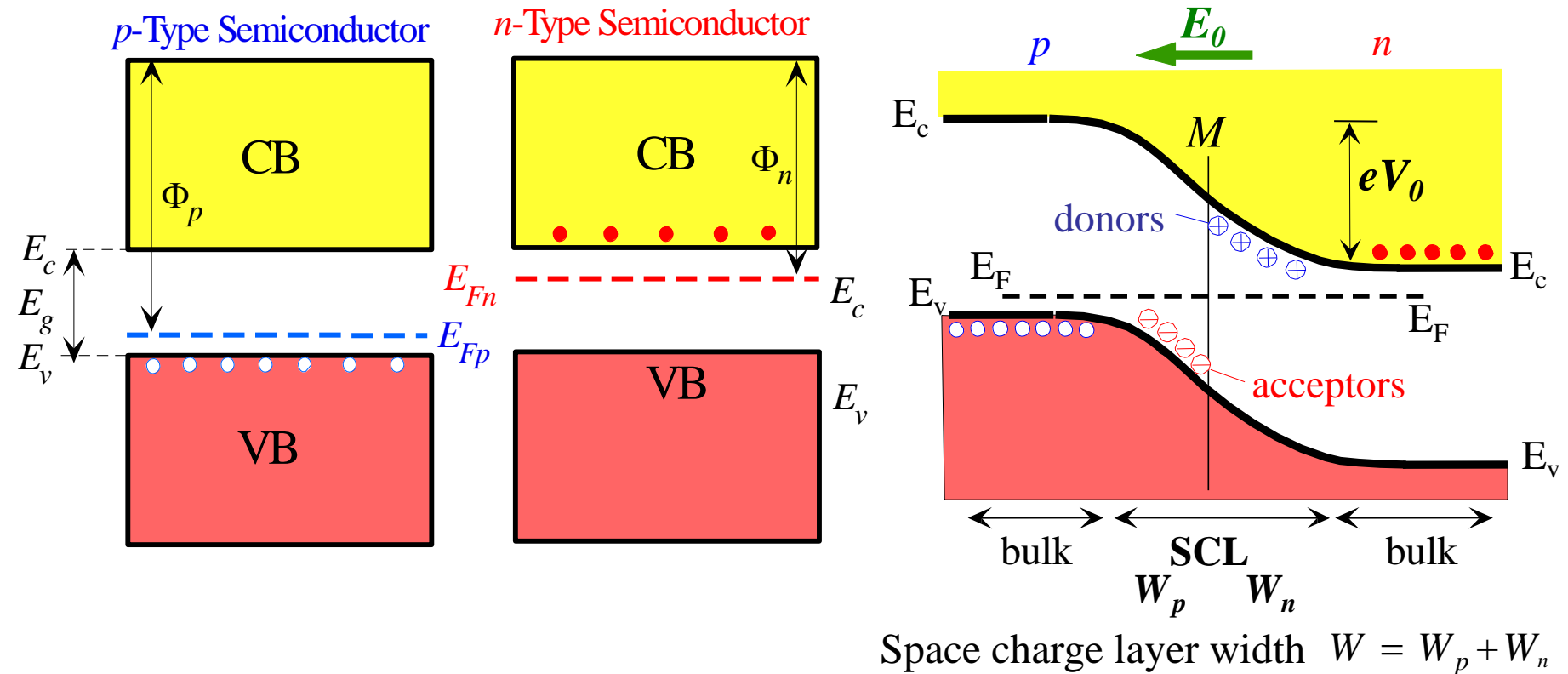
1. *metal-semiconductor*

- *Schottky Junction*
- *Ohmic Contact*

2. *semiconductor-semiconductor*

- *pn Junction (1)*
- ***pn Junction (2)***
- *Tutorial + metal oxide field-effect transistor (MOSFET)*

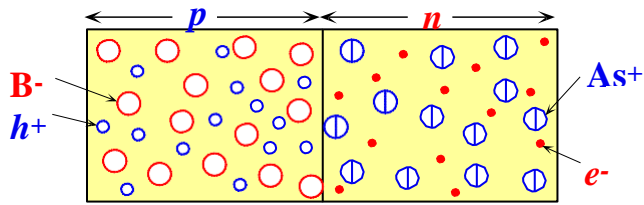
Band Diagram of pn Junction: No Bias (Open Circuit)



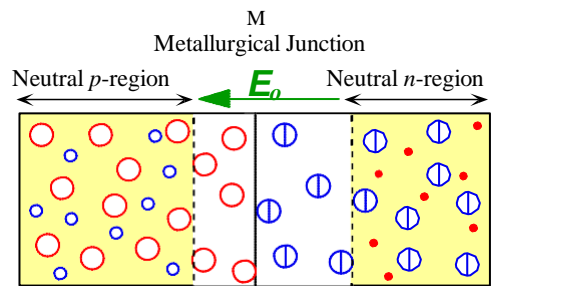
The region around the M contains the **space charge layer (SCL)**. On the *n*-side of M, SCL has the exposed positively charged donors whereas on the *p*-side it has the exposed negatively charged accepters.

SCL: space charge layer (空间电荷层) /depletion region/depletion layer (耗尽层)
 M: metallurgical junction (冶金结), Bulk (块体)

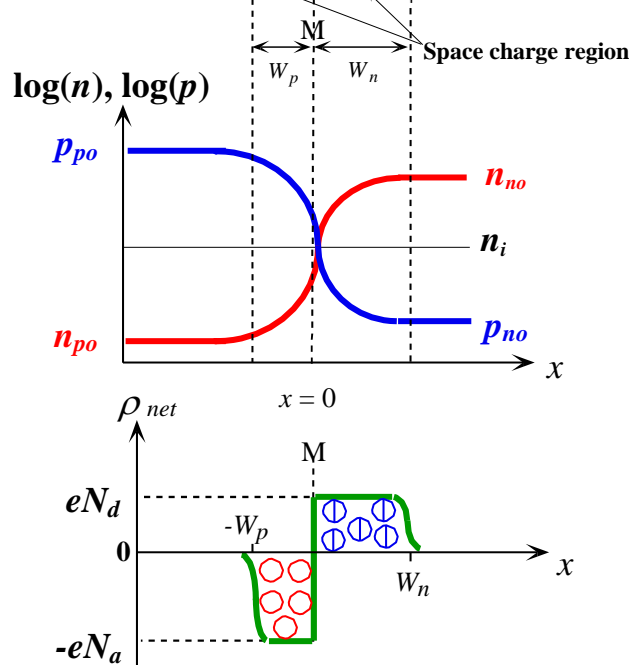
pn Junction: Space Charge Layer



Each electron moves over the interface will combine with one hole.



The total number of negative charge on p side equals to that of positive charge on n side to remain charge neutrality



p_{p0} : majority carrier concentration on p side

n_{p0} : minority carrier concentration on p side

p_{n0} : minority carrier concentration on n side

n_{n0} : majority carrier concentration on n side

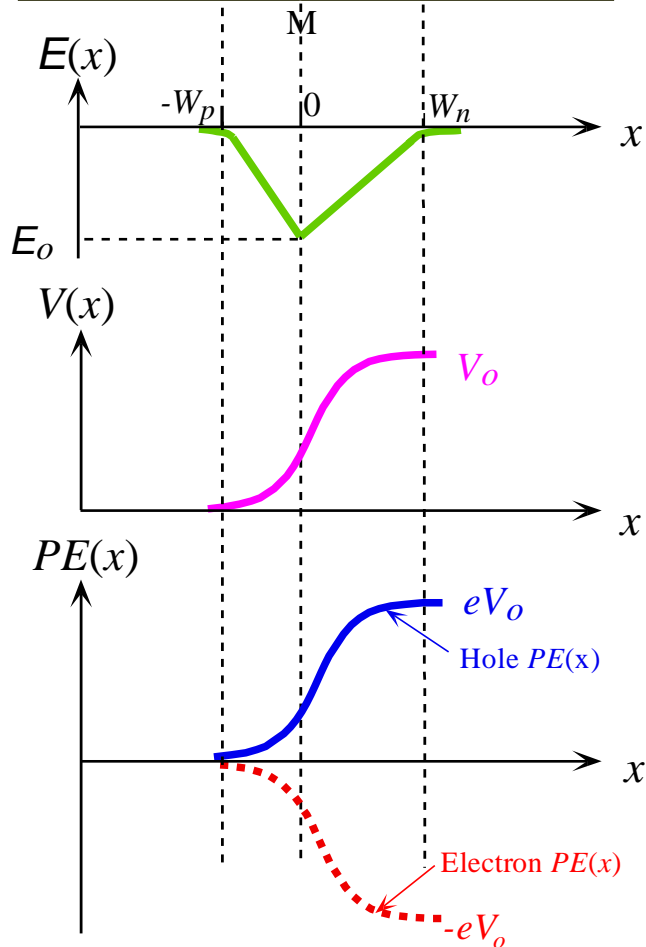
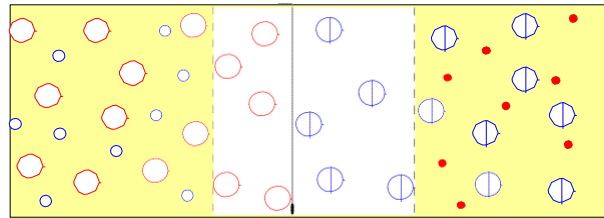
$$N_a W_p = N_d W_n$$

ρ_{net} : net space charge density

N : doping concentration

W : space charge layer width

pn Junction: Space Charge Layer



Gauss's law in point form:

ϵ_0 and ϵ_r : absolute and relative permittivity (介电常数) of the semiconductor material

$$\frac{dE}{dx} = \frac{\rho_{net}(x)}{\epsilon_r \epsilon_0} \longrightarrow E(x) = \frac{\rho_{net}}{\epsilon_r \epsilon_0} x + C_1$$

$$E_0 = -\frac{eN_d W_n}{\epsilon_r \epsilon_0} = -\frac{eN_a W_p}{\epsilon_r \epsilon_0}$$

The negative field means -x direction

$$E(x) = -\frac{dV}{dx} \longrightarrow V(x) = -\int_{-W_p}^x E(x) dx$$

By putting $x = W_n$

$$V_0 = \frac{1}{2} E_0 W_0 = \frac{eN_a N_d W_0^2}{2\epsilon_r \epsilon_0 (N_a + N_d)}$$

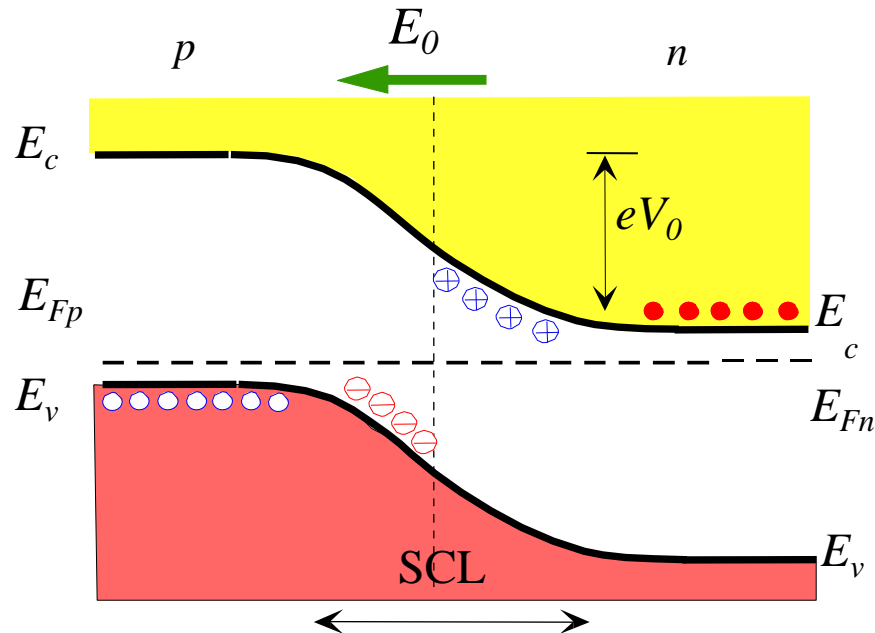
V_0 : the built-in potential (内置电位)

$W_0 = W_p + W_n$: the total width of the space charge layer under a zero applied voltage

pn Junction: Built-in Potential

Probability of electrons occupying energy E is determined by **Fermi-Dirac statistics**, which is reduced to **Boltzmann statistics** when $E - E_F \gg k_B T$, it demands the concentrations n_1 and n_2 of potential energies E_1 and E_2 are related by:

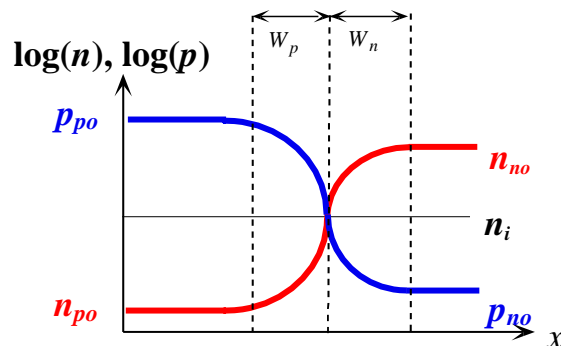
$$\frac{n_2}{n_1} = \exp\left[-\frac{(E_2 - E_1)}{kT}\right]$$



$$\frac{n_{po}}{n_{no}} = \exp\left(-\frac{eV_o}{k_B T}\right)$$

$$\frac{p_{no}}{p_{po}} = \exp\left(-\frac{eV_o}{k_B T}\right)$$

$$p_{po} = N_a \quad p_{no} = \frac{n_i^2}{n_{no}} = \frac{n_i^2}{N_d}$$



$$V_o = \frac{k_B T}{e} \ln\left(\frac{N_a N_d}{n_i^2}\right)$$

$$W_o = \sqrt{\frac{2\epsilon_o \epsilon_r (N_a + N_d) V_o}{e N_a N_d}}$$

Diffusion

Electron diffusion current density

$$J_{D,e} \propto -\frac{dn}{dx}$$
$$= eD_e \frac{dn}{dx}$$

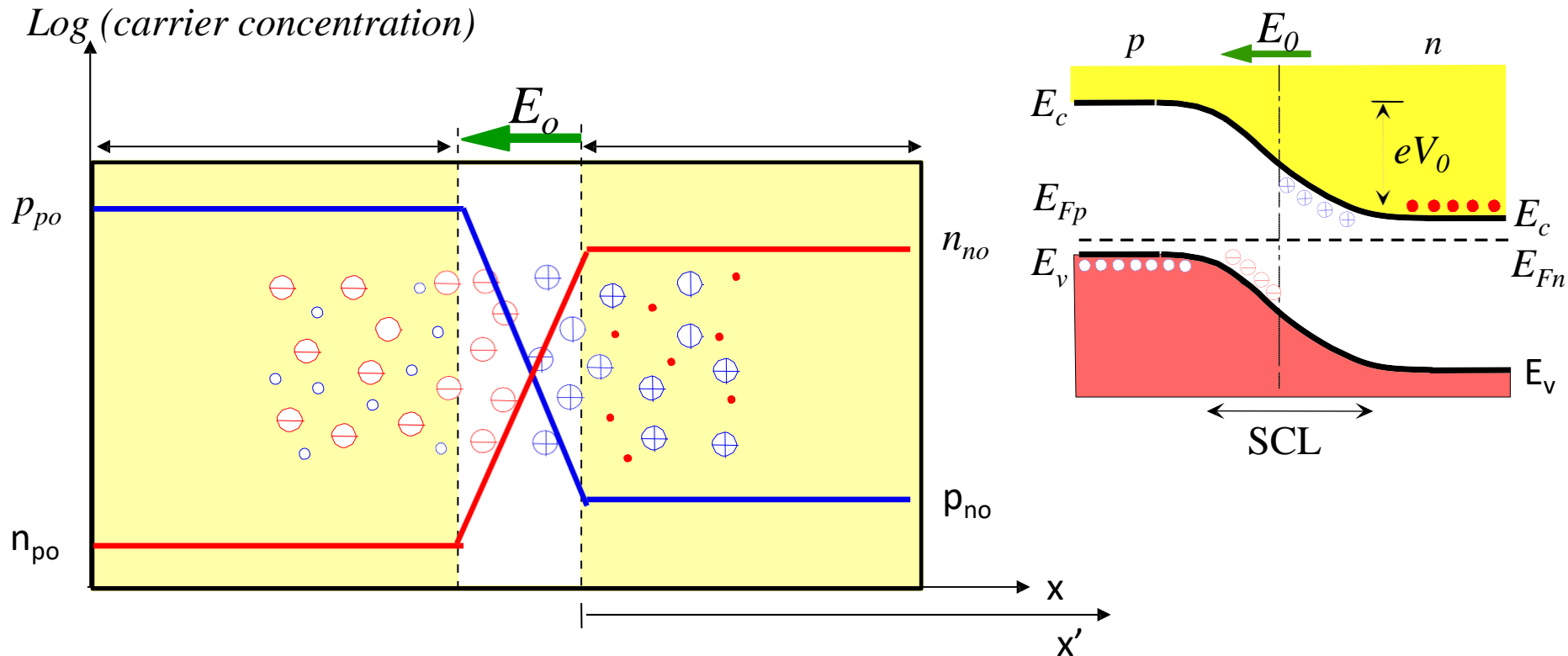
Hole diffusion current density

$$J_{D,h} \propto -\frac{dp}{dx}$$
$$= -eD_h \frac{dp}{dx}$$

Diffusion coefficient（扩散系数）， D_e or D_h , is a measure of the ease of carrier *diffusion* motion in a medium. Mobility, μ_e or μ_h , is a measure of the ease of carrier *drift* motion in a medium. The two quantities are related by the **Einstein Relation**.

$$\frac{D_e}{\mu_e} = \frac{kT}{e} \quad \text{and} \quad \frac{D_h}{\mu_h} = \frac{kT}{e}$$

Carrier Concentration Profiles Across a *pn* Junction: **No Bias**

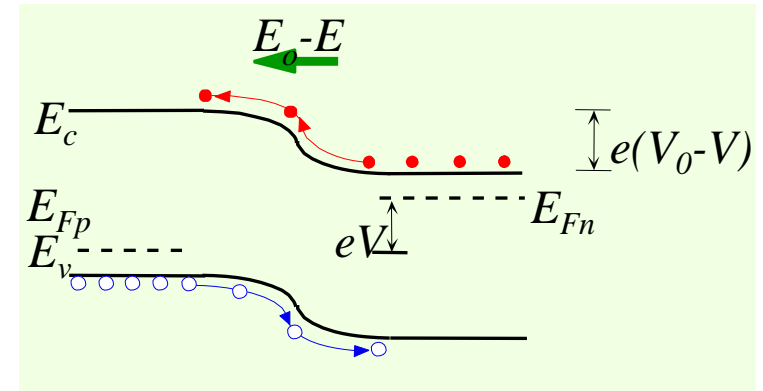
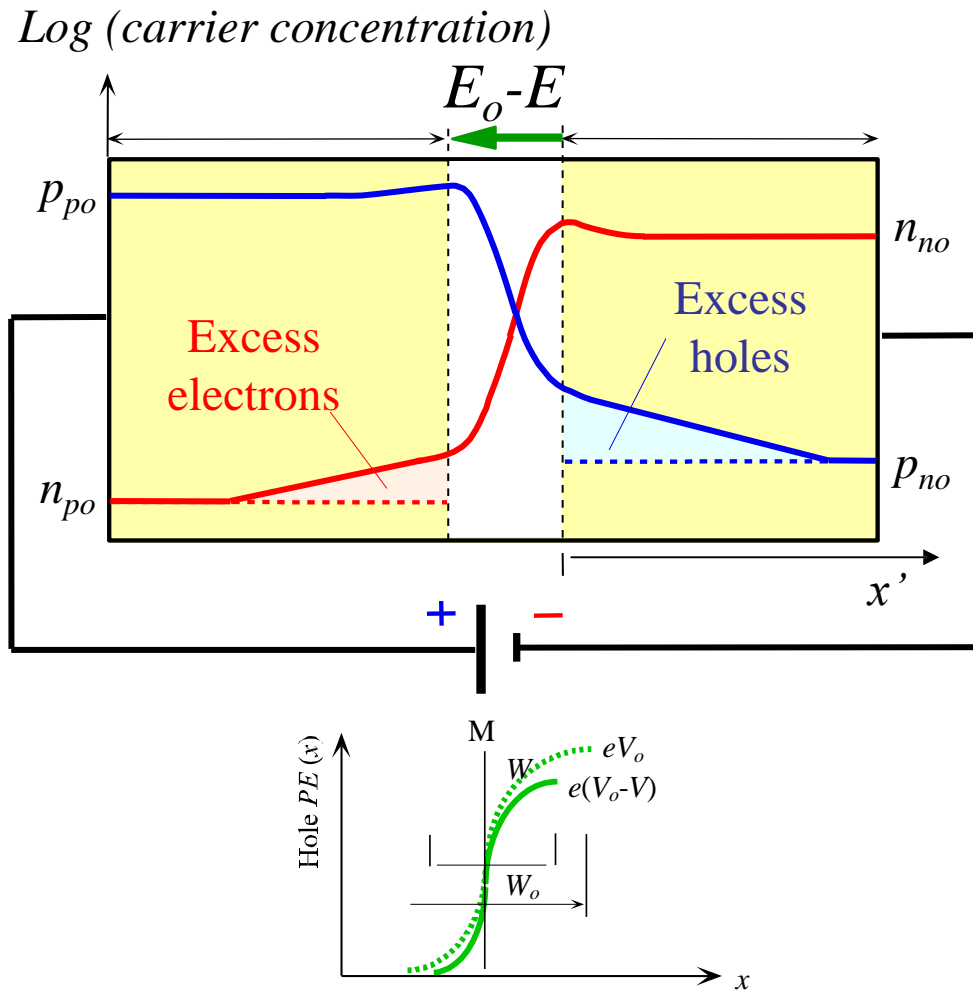


$$J_e = en\mu_e E_x + eD_e \frac{dn}{dx}$$

$$J_h = ep\mu_h E_x - eD_h \frac{dp}{dx}$$

When there is no electric field applied to a *pn* junction, there is no current. The diffusion current and drift current balance each other within the space charge layer.

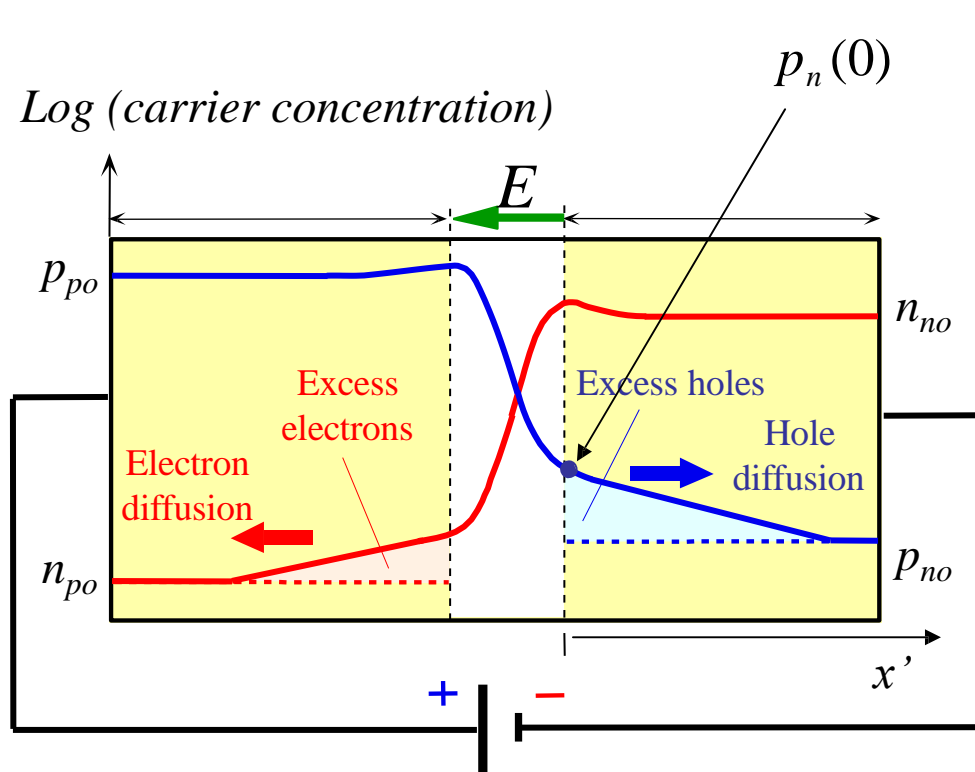
Carrier Concentration Profiles Across a *pn* Junction: Forward Bias



- (1) Voltage drops mainly across the SCL.
- (2) The potential barrier against diffusion is reduced to $(V_o - V)$.
- (3) The probability that a carrier will surmount the barrier becomes proportional to $\exp\left[-\frac{(V_o - V)}{k_B T}\right]$

More carriers can diffuse to the opposite sides of the junction. This is called the **injection of excess minority carriers** (少数载流子注入) .

Current Across a **Forward Biased** *pn* Junction: **Diffusion**



The **diffusion of minority carriers** contributes to the current density of a forward biased *pn* junction.

$$\frac{n_2}{n_1} = \exp\left[-\frac{(E_2 - E_1)}{kT}\right]$$

$$p_n(0) = p_n(x' = 0)$$

$$= p_{po} \exp\left[-\frac{e(V_o - V)}{k_B T}\right]$$

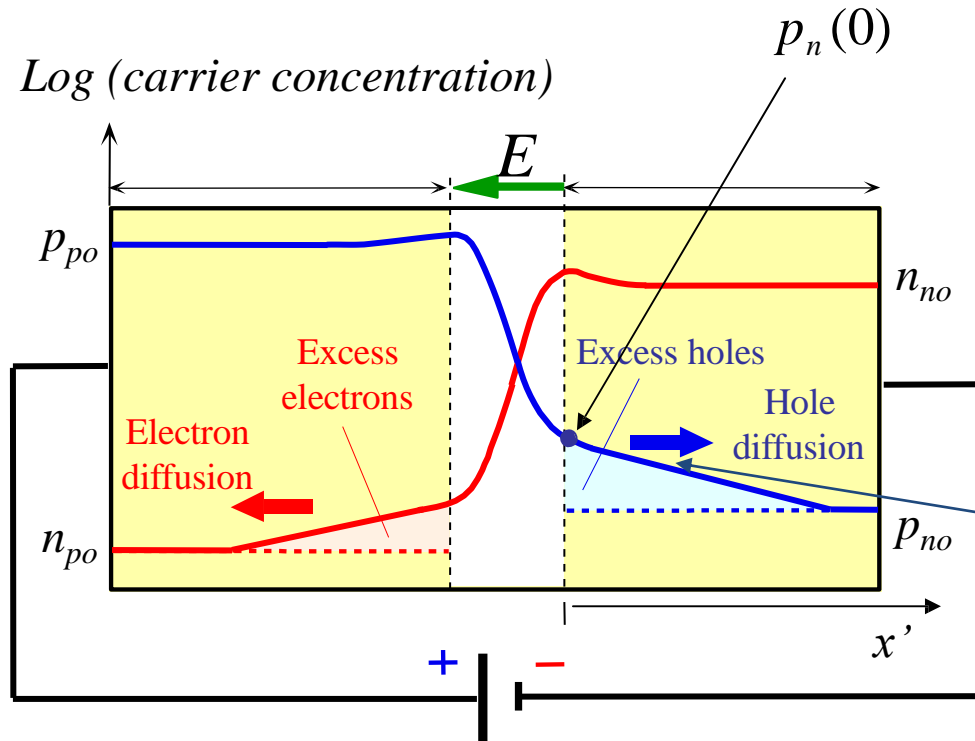
$$\frac{p_{no}}{p_{po}} = \exp\left(-\frac{eV_o}{k_B T}\right)$$

$$p_n(0) = p_{no} \exp\left[\frac{eV}{k_B T}\right]$$

Law of the junction

relates the injected minority carrier concentration just outside SCL to the applied voltage.

Current Across a **Forward Biased** *pn* Junction: **Diffusion**



Law of the junction

$$p_n(0) = p_{no} \exp\left[\frac{eV}{k_B T}\right]$$

$$J_{D,hole} = -eD_h \frac{dp_n(x')}{dx'}$$

hole concentration $p_n(x')$ fall **exponentially** toward the thermal equilibrium value p_{no}

$$\Delta p_n(x') = \Delta p_n(0) \exp\left(-\frac{x'}{L_h}\right)$$

Where: $\Delta p_n(x') = p_n(x') - p_{no}$

Minority Carrier **Diffusion Length**

$$L_h = \sqrt{D_h \tau_h}$$

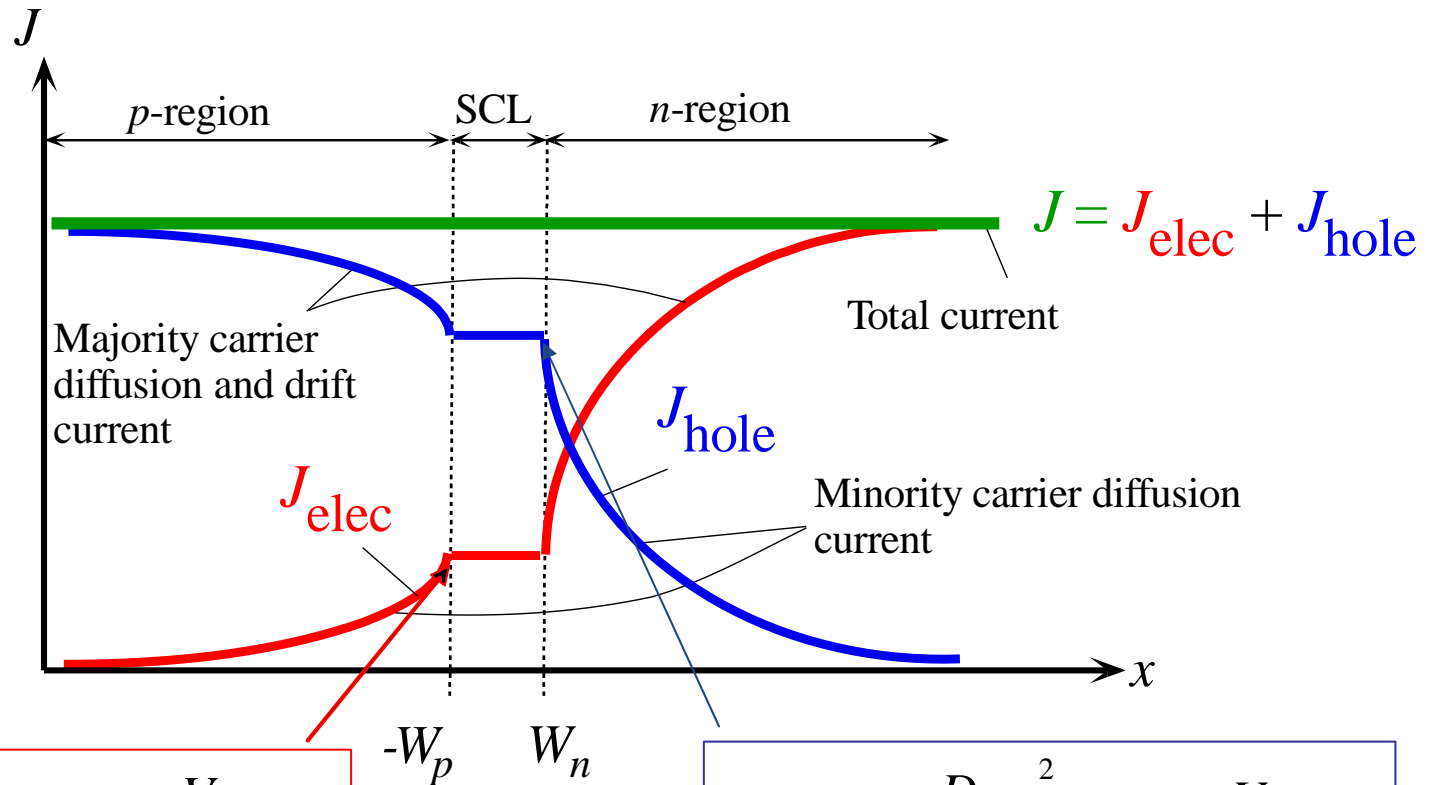
τ_h is the mean hole **recombination lifetime** (minority carrier lifetime) in the n-region

At $x' = 0$:

$$J_{D,hole} = \left(\frac{eD_h p_{no}}{L_h}\right) \left[\exp\left(\frac{eV}{k_B T}\right) - 1\right]$$

$$p_{no} = \frac{n_i^2}{n_{no}} = \frac{n_i^2}{N_d}$$

Total Diffusion Current: Electron and Hole



$$J_{D,elec} = \left(\frac{eD_e n_i^2}{L_e N_a} \right) \left[\exp\left(\frac{eV}{k_B T}\right) - 1 \right]$$

$$J_{D,hole} = \left(\frac{eD_h n_i^2}{L_h N_d} \right) \left[\exp\left(\frac{eV}{k_B T}\right) - 1 \right]$$

The total current anywhere in the device is constant.

Total Diffusion Current: Electron and Hole

$$J = J_{\text{elec}} + J_{\text{hole}}$$

$$J_{D,\text{elec}} = \left(\frac{eD_e n_i^2}{L_e N_a} \right) \left[\exp\left(\frac{eV}{k_B T}\right) - 1 \right]$$

$$J_{D,\text{hole}} = \left(\frac{eD_h n_i^2}{L_h N_d} \right) \left[\exp\left(\frac{eV}{k_B T}\right) - 1 \right]$$

$$J = \left(\frac{eD_e}{L_e N_a} + \frac{eD_h}{L_h N_d} \right) n_i^2 \left[\exp\left(\frac{eV}{k_B T}\right) - 1 \right]$$

$$J = J_{so} \left[\exp\left(\frac{eV}{kT}\right) - 1 \right]$$

**Ideal diode equation
(Shockley equation)**

$$J_{so} = \left[\left(\frac{eD_h}{L_h N_d} \right) + \left(\frac{eD_e}{L_e N_a} \right) \right] n_i^2$$

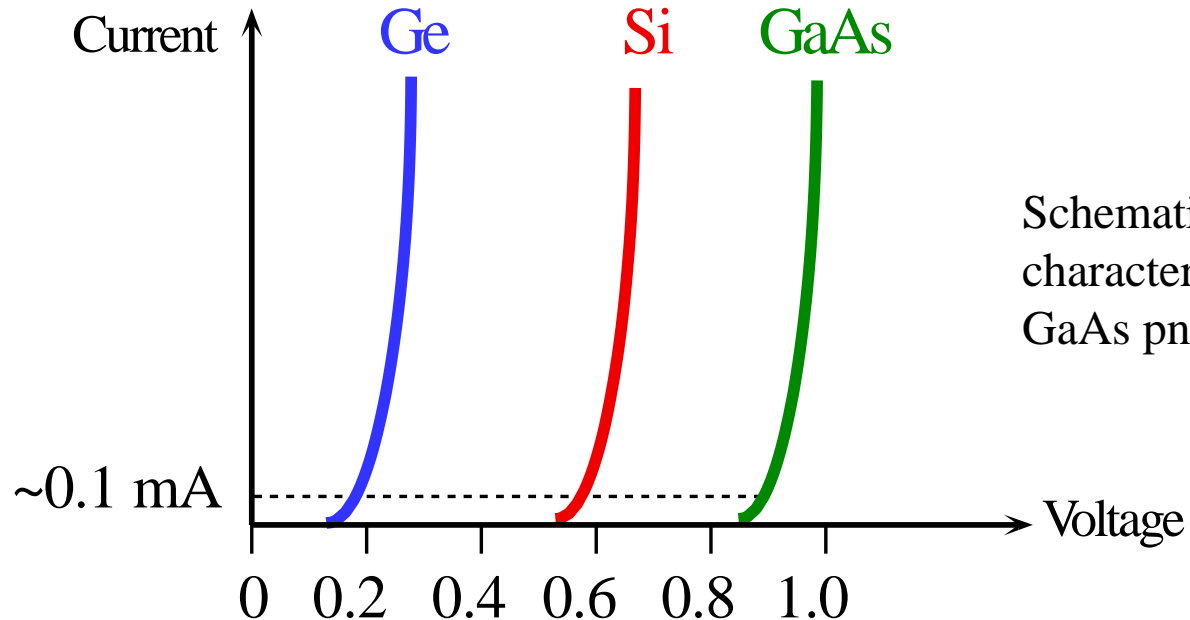
reverse saturation
current density

Total Diffusion Current: Electron and Hole

$$J = \left(\frac{eD_e}{L_e N_a} + \frac{eD_h}{L_h N_d} \right) n_i^2 \left[\exp\left(\frac{eV}{k_B T}\right) - 1 \right]$$

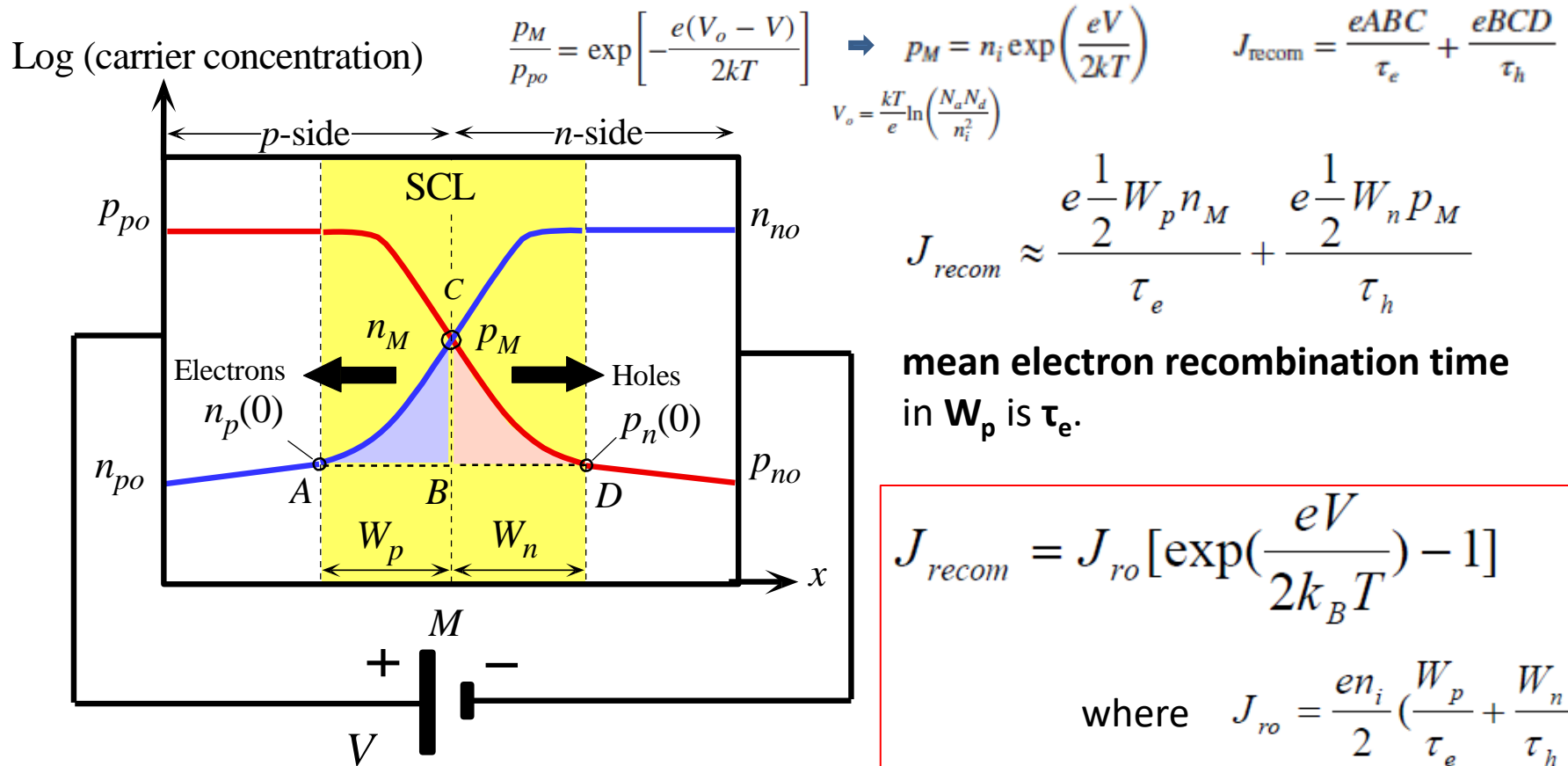
$$n_i^2 = N_c N_v \exp\left(-\frac{E_g}{k_B T}\right)$$

$$J \approx \left(\frac{eD_e}{L_e N_a} + \frac{eD_h}{L_h N_d} \right) N_c N_v \exp\left[\frac{e(V - V_g)}{k_B T}\right]$$



Schematic sketch of the I-V characteristics of Ge, Si and GaAs pn junction

Current Across a Forward Biased pn Junction: Recombination

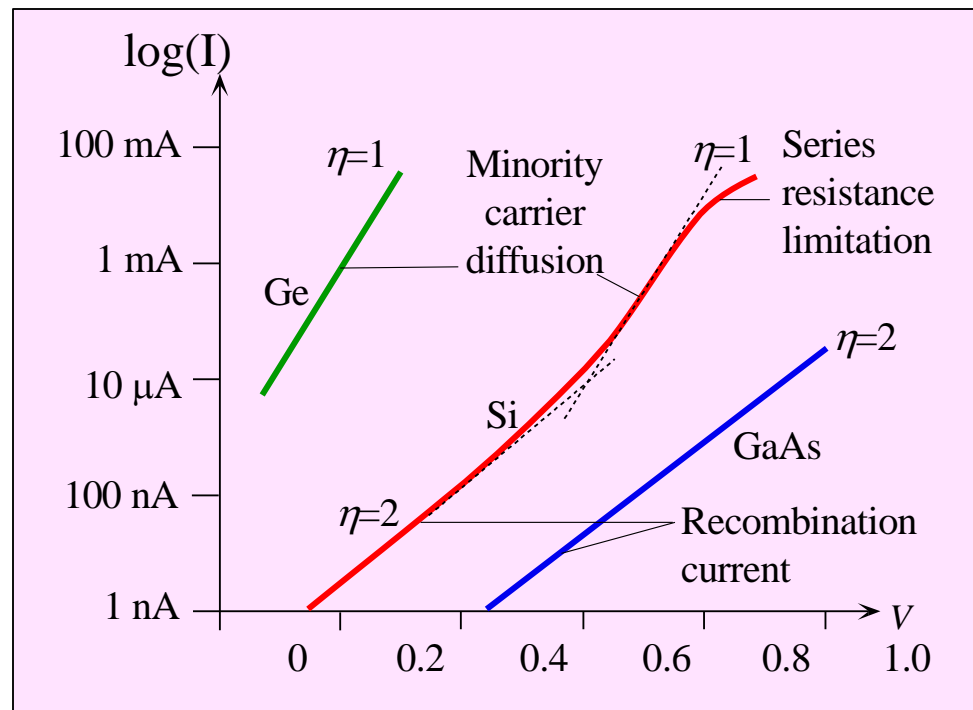


Forward biased pn junction: the injection of carriers and their recombination in the SCL

Total Current of a pn Junction under Forward bias

$$J = J_{so} \left[\exp\left(\frac{eV}{k_B T}\right) - 1 \right] + J_{ro} \left[\exp\left(\frac{eV}{2k_B T}\right) - 1 \right]$$

$$J \approx J_{so} \exp\left(\frac{eV}{k_B T}\right) + J_{ro} \exp\left(\frac{eV}{2k_B T}\right)$$

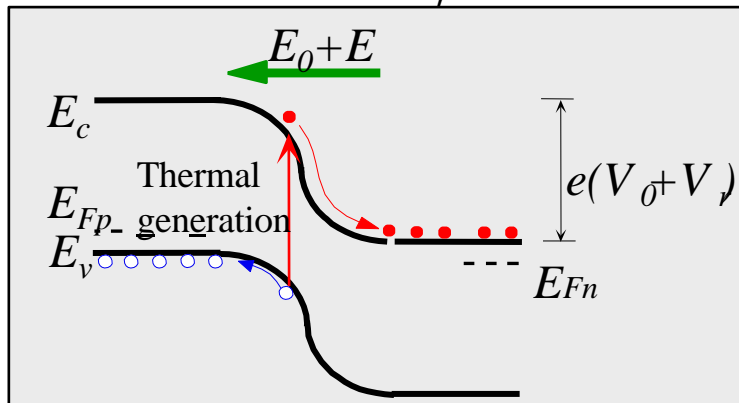
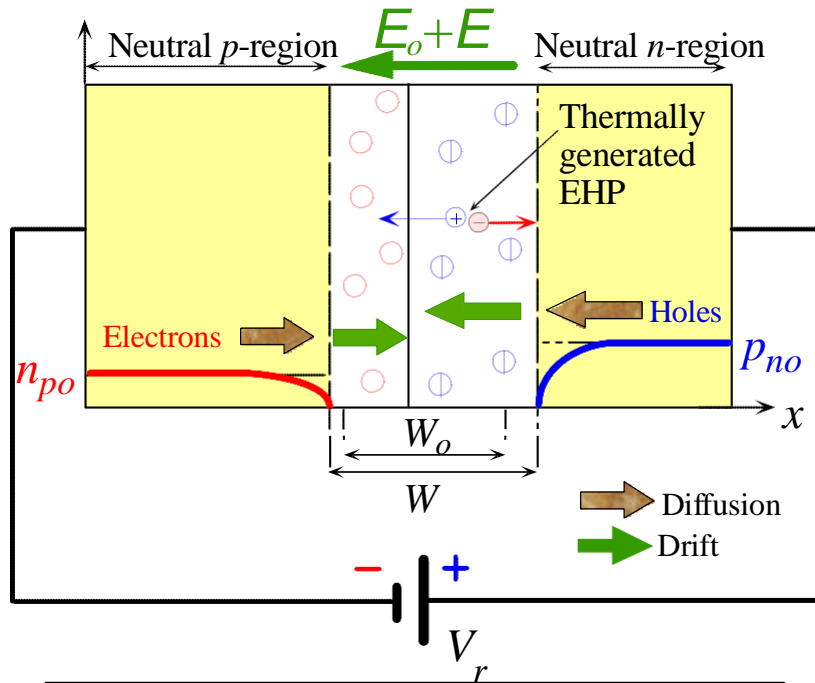


$$I = I_o [\exp(eV/\eta kT) - 1]$$

Schematic sketch of typical I-V characteristics of Ge, Si and GaAs *pn* junctions as $\log(I)$ vs. V . the slope indicates $e/(\eta k_B T)$ η : *ideality factor*

Current Across a pn Junction: **Reverse Bias**

Minority Carrier



(a) Minority carrier extracted and swept by the field across the SCL

Essentially **Shockley equation**:

$$J = \left(\frac{eD_e}{L_e N_a} + \frac{eD_h}{L_h N_d} \right) n_i^2 \left[\exp\left(\frac{eV}{k_B T}\right) - 1 \right]$$

$$\approx - \left(\frac{eD_e}{L_e N_a} + \frac{eD_h}{L_h N_d} \right) n_i^2$$

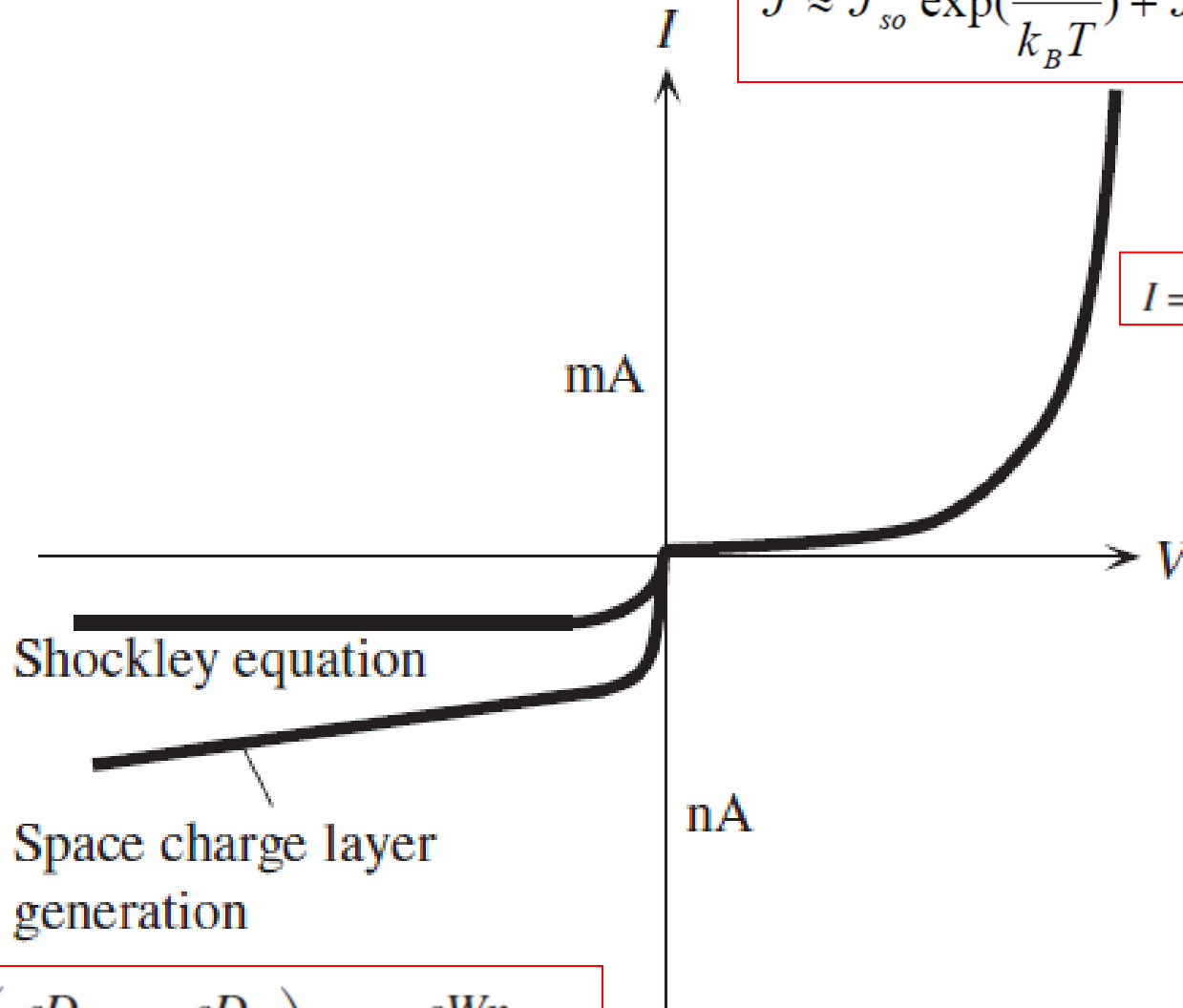
reverse saturation current density, $-J_0$
independent of voltage V_r

(b) Electron-hole pair (EHP) thermally generated within the SCL.

$$J_{gen} = \frac{eWn_i}{\tau_g}$$

τ_g is the mean time to generate an EHP

I-V Response of a *pn* Junction



$$J \approx J_{so} \exp\left(\frac{eV}{k_B T}\right) + J_{ro} \exp\left(\frac{eV}{2k_B T}\right)$$

$$I = I_o [\exp(eV/\eta kT) - 1]$$

$$J_{\text{rev}} = \left(\frac{eD_h}{L_h N_d} + \frac{eD_e}{L_e N_a} \right) n_i^2 + \frac{eW n_i}{\tau_g}$$

完成并提交 **Assignment 6.3 (1)**

Assignment 6.3 (2)无须提交，在5月12日习题课前尽量完成

提交时间： **5月12日（周一）**中午前提交**Assignment 6.3 (1)**

提交方式：电子版（写明姓名、学号），通过本班课代表
统一提交